

SOD-323

" (SR\ P H H W V 8 / 9 I O D P P D E L O L W \ U D W  
" 0 R L V W X U H 6 H Q V L W L Y L W \ / H Y H O

AYW\Ub]WU`8UhU`

DUW\_U[Y: SOD323`

HYf a ]bU`g: Tin plated leads, solderable per`  
J-STD-002 and JESD22-B102

Dc`Uf]hm.`Cathode line denotes the cathode end

Auf\_]b[. ZF

AUI]a i a`FUh]b[g

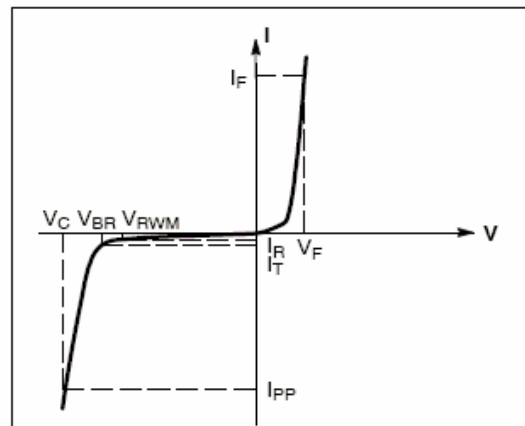
D5F5A9H9F`	GMA6C@`	@=A-HG`	
	>/ Hh;`	! ( )`hc` Z %&`	
IEC61000-4-2(ESD)Air	V <sub>ESD</sub> <sup>1</sup>	± 30	KV
IEC61000-4-2(ESD)Contact		± 30	KV
Peak Pulse Current, t <sub>P</sub> =8/20µs	I <sub>PP</sub> <sup>2</sup>	15	A

Peak Power Dissipation, t<sub>P</sub>=8/

orm according to IEC61000-4-5.

9`YWhf]WU`DUfU a YhYf

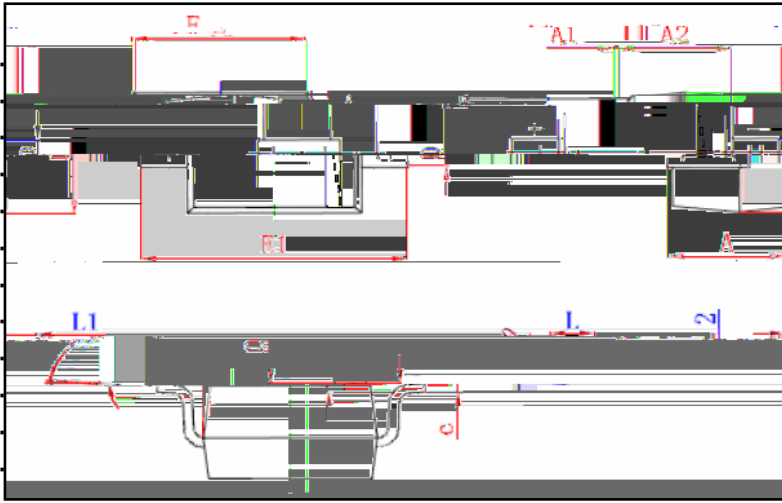
D5F5A9H9F`	GMA6C@`
Clamping Voltage@ I <sub>PP</sub>	V <sub>C</sub>
Breakdown Voltage@ I <sub>T</sub>	V <sub>BR</sub>
Peak Pulse Current	I <sub>PP</sub>
Test Current	I <sub>T</sub>
Reverse Leakage Current@ V <sub>RWM</sub>	I <sub>R</sub>
Reverse Standoff Voltage	V <sub>RWM</sub>
Forward Voltage@ I <sub>F</sub>	V <sub>F</sub>
Forward Current	I <sub>F</sub>
Peak Power Dissipation	P <sub>PK</sub>
Junction Capacitance @ V <sub>R</sub> =0 and f=1MHz Of a amgj Oc=	C <sub>j</sub>



v(OHFWULFDO &KÄD DFWISQOHVDFR WKHUZÄVH VSHFLILHG  

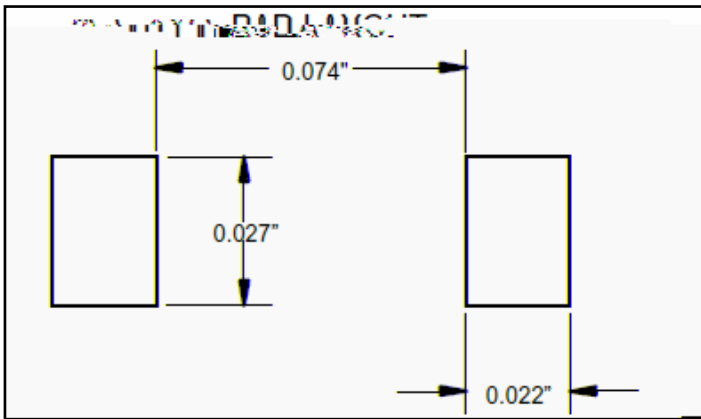



C i`h`bY`8] a Ybg]cbg`



Layer	Thickness	Material	Start Z	End Z
A	1.000	A	0.000	1.000
A1	0.100	A1	1.000	1.100
A2	0.900	A2	1.100	2.000
b	0.400	b	2.000	2.400
E1	2.500	E1	2.700	5.200

Gc`XYf]b [ ` : cchdf]bh`



Unit inches



“9G8 )J\$8 ”

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8]gW'U]a Yf`  
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